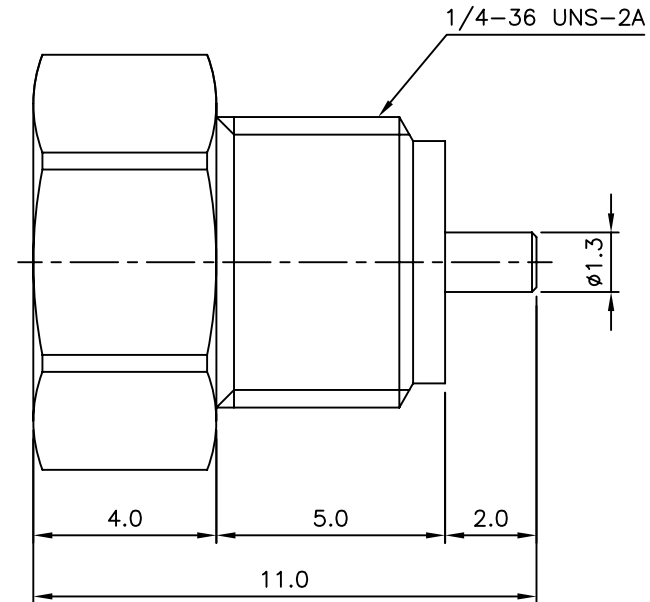
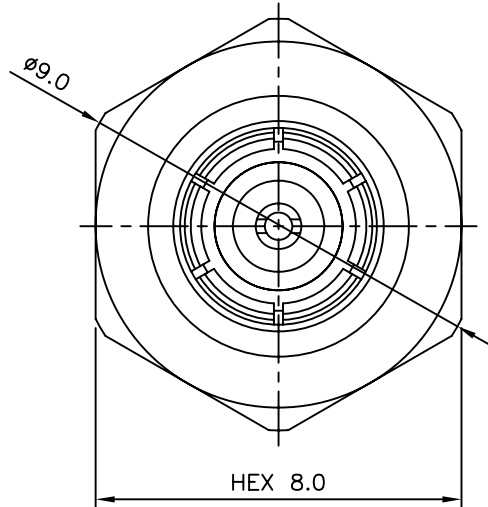


REVISION						
REV	DESCRIPTION			DRAWN	APPR	DATE
IR	Initial Registration			E.H.KIM	I.C.KIM	2014.02.10.
1	[설번처리 No.201504-0003] BODY, JACK 표준화 치수 적용			H.J.LEE	I.C.KIM	2015.04.22.



4	INSULATOR	1	TEFLON		DIN02042-N/1
3	CONTACT	1	BeCu	Gold Plate	DCT02637-5/1
2	JACK	1	MBsBD	Gold Plate	DJA00159-5/4 DJA00159-5/3
1	BODY	1	MBsBD	Gold Plate	DBD03115-5/2
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2015. 04. 22.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE SMBL50 SOLDER END PB (F/F)
		DRAWN BY	H.J.LEE	
FINISH		SCALE	6/1	A4 DWG NO. CN02833-7/3 REVISION 1 SHEET 1 of 1
		UNIT	mm	